VBsemi

FSL3306-VB TO262F Datasheet

N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]
60	0.003 at V_{GS} = 10 V	210
	0.005 at V_{GS} = 4.5 V	185

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:

RoHS
COMPLIANT

**I²PAK
(TO-262)**

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current (T_J = 175 °C)[b]	T_C = 25 °C	I_D	210	A
	T_C = 100 °C		185[a]	
Pulsed Drain Current		I_{DM}	200	
Continuous Source Current (Diode Conduction)		I_S	180[a]	
Avalanche Current		I_{AS}	70	
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E_{AS}	125	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	136	W
	T_A = 25 °C		3[b], 8.3[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[a]	t $\leq$ 10 sec	R_{thJA}	15	18	°C/W
	Steady State		40	50	
Maximum Junction-to-Case		R_{thJC}	0.85	1.1	

Notes:
a. Package limited.
b. Surface mounted on 1" x 1" FR4 board.
c. t $\leq$ 10 s.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

| Parameter	Symbol	Test Conditions	Min.	Typ.[a]	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	60			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1	2	3	V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			1	µA
		V_{DS} = 60 V, V_{GS} = 0 V, T_J = 125 °C			50	
		V_{DS} = 60 V, V_{GS} = 0 V, T_J = 175 °C			250	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	60			A
Drain-Source On-State Resistance[b]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 20 A		0.003		Ω
		V_{GS} = 10 V, I_D = 20 A, T_J = 125 °C		0.008		
		V_{GS} = 10 V, I_D = 20 A, T_J = 175 °C		0.010		
		V_{GS} = 4.5 V, I_D = 15 A		0.005		
Forward Transconductance[b]	g_{fs}	V_{DS} = 15 V, I_D = 20 A		60		S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		2650		pF
Output Capacitance	C_{oss}			470		
Reverse Transfer Capacitance	C_{rss}			225		
Total Gate Charge[c]	Q_g	V_{DS} = 30 V, V_{GS} = 10 V, I_D = 50 A		47	70	nC
Gate-Source Charge[c]	Q_{gs}			10		
Gate-Drain Charge[c]	Q_{gd}			12		
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = 30 V, R_L = 0.6 Ω $I_D \cong$ 50 A, V_{GEN} = 10 V, R_g = 2.5 Ω		10	20	ns
Rise Time[c]	t_r			15	25	
Turn-Off Delay Time[c]	$t_{d(off)}$			35	50	
Fall Time[c]	t_f			20	30	
Source-Drain Diode Ratings and Characteristics (T_C = 25 °C)						
Pulsed Current	I_{SM}				60	A
Diode Forward Voltage	V_{SD}	I_F = 20 A, V_{GS} = 0 V		1	1.5	V
Reverse Recovery Time	t_{rr}	I_F = 20 A, di/dt = 100 A/µs		45	100	ns

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C unless noted)

Output Characteristics

Transfer Characteristics

Transconductance
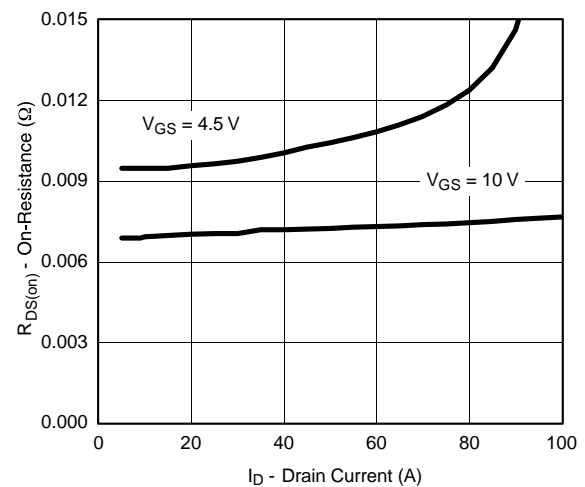
On-Resistance vs. Drain Current

Capacitance

Gate Charge

TYPICAL CHARACTERISTICS (25 °C unless noted)

$V_{GS} = 10$ V
$I_D = 20$ A
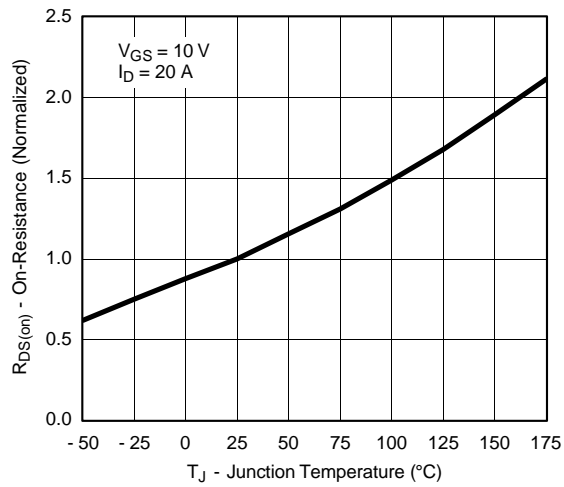
On-Resistance vs. Junction Temperature

$T_J = 150$ °C

$T_J = 25$ °C
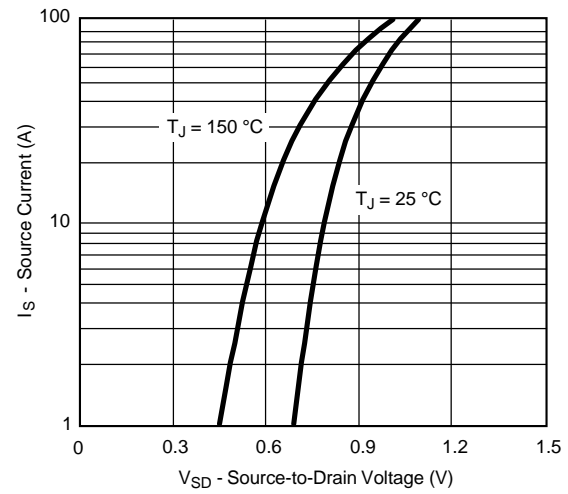
Source-Drain Diode Forward Voltage

THERMAL RATINGS

Maximum Drain Current vs. Ambient Temperature

* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

Normalized Thermal Transient Impedance, Junction-to-Case

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